# Tuesday, June 19<sup>th</sup> PI FNARY

#### 9:30 a.m. WELCOME - REGISTRATION

#### Filling the Gap from Design to Application

10:00 a.m. Leti's Vision: Dr L.Malier, CEA-Leti

10:30 a.m. Large-Scale Integrated Photonics for High-Performance Interconnects: Moore's Law for Photonics in High-Performance Data Centers: R.Beausoleil, HP Labs

11:00 a.m. Semicon for Power Devices: B. Murari, STM Scientific Advisor

11:30 a.m. Semicon for Healthcare: S.Picaud, Institut de la vision

12:00 a.m. Semicon for Automotive: D.Griot, DNG Conseil

12:30 a.m. LUNCH

#### Modelling the Application Landscape Through Technology

2:00 p.m. Energy Management systems: S.Dauvé, CEA-Leti

2:20 p.m. Internet of Things: L.Hérault, CEA-Leti

2:40 p.m. Optimizing the Brain Computer Interface: Dr D.Lobel,

3:00 p.m. Human Machine Interfaces and their Evolutions: S.Cina, CEA-Leti

3:20 p.m. BREAK 30'

### Venturing the future with success stories

4:00 p.m. Start-ups & Leti, Success & Ambition: Dr L.Malier, CEA-Leti

4:20 p.m. APIX: J-P.Braun

4:40 p.m. BeSpoon: J-M.André

5:00 p.m. Multix: P.Radisson

5:20 p.m. Fluoptics: O. Allard & Ph.Rizo

## Closing: 20 years of thinking, 20 years ahead

Since 1992, Soitec built its reputation in generating revolutionary semiconductor materials and strove for leadership in performance and energy efficiency innovation. Soitec technologies are at the

heart of today's most critical challenges of energy savings and green energy production that will launch sustainable markets.

5:50 p.m. A-J. Auberton-Hervé, Soitec

6:20 p.m. END

8:15 p.m. GALA DINNER

Restaurant Le Téléphérique, Fort de la Bastille



# Wednesday, June 20th \\\\ MORNING

830 a.m. WELCOME COFFEE

#### Microelectronics and microsystems components and technologies



semiconductor business is assimilating Emerging Technologies to face the various scaling challenges or strengthen new applications areas. Sufficient maturity is gained by Nanoelectronics to introduce new architectures featuring neuromimetism, reconfigurability at a high level with low power consumption or highly integrated sensing. This happens in the frame of a strong demand for energy and its management, such as n automotive or transportation, illustrated here.

9.00 a.m. Welcome: Dr S.Deleonibus, CEA-Leti

9:10am. Restructuring of Memory Hierarchy in System and No-Standby-Power Nonvolatile Logic with STT-MRAM Technology: Dr. T.Endoh, Univ Tohoku

9:40 a.m. Advanced Embedded Memories: B.De Salvo, CEA-Leti 10:10 a.m. NEMS from Components Research to Applications: P.Puaet, APIX

10:40 a.m. BREAK 30'

11:10a.m. Power Electronic Components for Future Automotives and Mobility: F.Kawai, Toyota Motors

11:40 a.m. GaN/Si power electronics: From devices to modules:

12:10a.m. LUNCH

8:30 a.m. WELCOME COFFEE

#### Advanced IC Design for Green IT

B

The main driver for semiconductor has moved from only Cost/performance tradeoff, to energy efficiency and extreme miniaturization due to portability and long battery lifetime requirements of mobile computing. To reach the required objectives circuit design solutions need to be aligned with both fabrication technologies and applications.

This session introduces key technologies for mastering future generations of system on chips (SoC) that require energy efficient computing, RF

9:00 a.m. Welcome: Dr A.Jerraya, CEA-Leti

9:10am. Green Computing: John Goodcare, ARM

9:40 a.m. Evolution of short range communication, NFC and others: B.Charrat, Inside Secure

10:10 a.m. 3D Integration for Energy Efficient Computing: D Dutoit CFA-Let

10:40 a.m. BREAK 30

11:10 a.m. Green RF Design: E.Mercier, CEA-Leti

11:40 a.m. Going Green With Image Sensors: A.Dupret, CEA-Leti

12:10 a.m. LUNCH

8:30 a.m. WELCOME COFFEE

## **Cyber Security**

ROOM 222-224



ybersecurity is a key challenge for the today and uture connected world. It is assumed that secure hardware components offer a real improvement for securina more complex systems, from user identification and authentication (e-banking, e-identity), up to computers or mobile devices (Trusted computing) However, even secure components are subject to attacks and security should be continuously improved. This session intends to highlight the key actors needs and to place the CEA- Leti's research works

9:00 a.m. Welcome: A.Merle, CEA-Leti

Cyber security of the armed forces, new threats & new technical issues: G.Poupard, DGA

9:40 a.m. Cyber Security, Emerging Threats, Efficient Solutions & Research Challenges: L.Duflot, ANSSI

10:10 a.m. Cyber Defence: J-P.Quémard, Cassidian

10:40 a.m. BREAK 30'

11:10 a.m. Attacks on Secure Devices: J.Cledière, CEA-Leti

11:40 a.m. What's new in secure device protections?: A.Tria,

12:10 a.m. LUNCH



# Wednesday, June 20th \\\\\ AFTERNOON

#### Biomedical



Delivering biological or chemical therapeutics is a major part of medical therapy. It can be envisaged by using delivery systems or delivery devices, ranging from nanoscale to macroscale. New developments in physics, chemistry and engineering enable the design of highly innovative delivery systems or revisit

his session will cover some of the most significant technological developments or address the next frontiers to deliver innovative therapeutics like small cheical entities, biopharmaceuticals or human cells

Welcome: Dr P.Boisseau, CEA-Leti

From Therapeutic Molecules to Therapeutic Solutions: P.Ferrara, Sanofi-Aventis

Latest Development in Nanodelivery Systems: N.Desai,

Lipidots® lipid nano dropplets: Dr I.Texier, CEA-Leti

Delivery Device for Biotherapies: D.Hoarau,

Microencapsulation of Human Cells: J.Oberholzer, **UIC Chicago** 

Micro-Pump for Drug Delivery: Dr R.Campagnolo,

5:45 p.m. FINAL CONCLUSION: Dr L.Malier, CEA-Leti

6:00 p.m. END

## **Photonics**



evolution performance nunication networks and computing requires increasing communication andwidth at all interconnects levels. Photonic echnology is considered as a means to overcome the interconnect bottleneck by utilizing optical nks to replace the long metallic wires.

**GRAND SALON** 

his session will review the application roadmaps and the different challenges that silicon photonics is facing in terms of materials, fabrication and

2:00 p.m. Welcome: L.Fulbert, CEA-Leti

2:10 p.m. Optical Interconnection / Polymer Waveguide Integrated Package: H.Yonekura, Shinko

Kotura Silicon Photonics, a WDM Approach to Optical Interconnect: J-L.Malinge, Kotura

Challenges & Opportunities for Optical Interconnects in Computing: B.Offrein, IBM Zurich

3:40 p.m. BREAK 30'

4:10 p.m. 3D Integration & Silicon Photonics for Green IT: Dr A.Jerraya,

4:35 p.m. Silicon Photonics Developments at ST: STMicroelectronics 5:00 p.m. Silicon Photonics, from Design to Circuits: S.Menezo, CEA-Leti

Technology Developments for Silicon Photonics: J-M.Fedeli,

5:45 p.m. FINAL CONCLUSION: Dr L.Malier, CEA-Leti

Smart Systems

ROOM 222-224



day, the integration of Smart Systems into our daily ives opens many ways for innovating to the industry ousing, lighting, eHealth, transportations... CEA-Leti has developed methodologies for driving the nnovation process from the concept to the product: dentification of the sweet spot, integration of most advanced technologies and support for dustrialization. nis session will present real life examples of Smart

stems and will, then, focus on one of the most

2:00 p.m. Welcome: C.Soubeyrat, CEA-Leti

2:10 p.m. Transfering Technological Value to SME: Pepite's Model: T.Delhome, CEA-Leti

2:40 p.m. Autonomous Roller Blind: T.Fritsch, Bubbendorf

3:10 p.m. Smart Device for Observance: C.Sivera, INLAB

3:40 p.m. BREAK 30'

4:10 p.m. Movea® Motion Intelligence Makes Sports and Fitness Fun ": B.Flament, Movea

4:40 p.m. Vibration Energy Harvesting: toward autonomous Wireless Sensor Nodes for Industry: S.Boisseau, CEA-

5:10 p.m. Smart Lighting: A.Lagrange, CEA-Leti

5:45 p.m. FINAL CONCLUSION: Dr L.Malier, CEA-Leti